

FEATURES

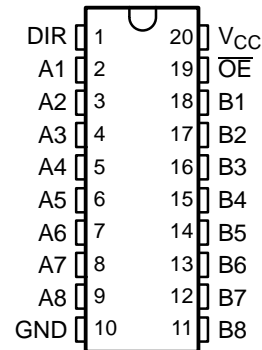
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.3 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

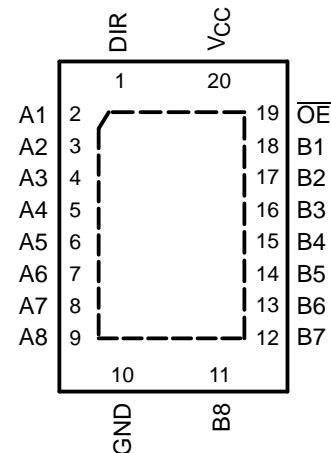
This octal bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses effectively are isolated.

DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 20	SN74LVC245AN	SN74LVC245AN
	QFN – RGY	Reel of 1000	SN74LVC245ARGYR	LC245A
	SOIC – DW	Tube of 25	SN74LVC245ADW	LVC245A
		Reel of 2000	SN74LVC245ADWR	
	SOP – NS	Reel of 2000	SN74LVC245ANSR	LVC245A
	SSOP – DB	Reel of 2000	SN74LVC245ADBR	LC245A
	TSSOP – PW	Tube of 70	SN74LVC245APW	LC245A
		Reel of 2000	SN74LVC245APWR	
		Reel of 250	SN74LVC245APWT	
	TVSOP – DGV	Reel of 2000	SN74LVC245ADGVR	LC245A
VFBGA – GQN	Reel of 1000	SN74LVC245AGQNR	LC245A	
VFBGA – ZQN (Pb-Free)		SN74LVC245AZQNR		

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	6.5	V
V_I	Input voltage range ⁽²⁾	-0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current		±50	mA
	Continuous current through V_{CC} or GND		±100	mA
θ_{JA}	Package thermal impedance	DB package ⁽⁴⁾	70	°C/W
		DGV package ⁽⁴⁾	92	
		DW package ⁽⁴⁾	58	
		GQN/ZQN package ⁽⁴⁾	78	
		N package ⁽⁴⁾	69	
		NS package ⁽⁴⁾	60	
		PW package ⁽⁴⁾	83	
	RGY package ⁽⁵⁾	37		
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.
- (5) The package thermal impedance is calculated in accordance with JESD 51-5.

SN74LVC245A
OCTAL BUS TRANSCEIVER
WITH 3-STATE OUTPUTS

SCAS218T–JANUARY 1993–REVISED FEBRUARY 2005

Recommended Operating Conditions⁽¹⁾

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C TO } 85^\circ\text{C}$		UNIT	
		MIN	MAX	MIN	MAX		
V_{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		
V_{IH}	High-level input voltage	$V_{CC} = 1.65\text{ V to } 1.95\text{ V}$	$0.65 \times V_{CC}$		$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	1.7		1.7		
		$V_{CC} = 2.7\text{ V to } 3.6\text{ V}$	2		2		
V_{IL}	Low-level input voltage	$V_{CC} = 1.65\text{ V to } 1.95\text{ V}$	$0.35 \times V_{CC}$		$0.35 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	0.7		0.7		
		$V_{CC} = 2.7\text{ V to } 3.6\text{ V}$	0.8		0.8		
V_I	Input voltage	0	5.5	0	5.5	V	
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V	
I_{OH}	High-level output current	$V_{CC} = 1.65\text{ V}$	-4		-4		mA
		$V_{CC} = 2.3\text{ V}$	-8		-8		
		$V_{CC} = 2.7\text{ V}$	-12		-12		
		$V_{CC} = 3\text{ V}$	-24		-24		
I_{OL}	Low-level output current	$V_{CC} = 1.65\text{ V}$	4		4		mA
		$V_{CC} = 2.3\text{ V}$	8		8		
		$V_{CC} = 2.7\text{ V}$	12		12		
		$V_{CC} = 3\text{ V}$	24		24		
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–40°C TO 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OH}	I _{OH} = –100 μA	1.65 V to 3.6 V	V _{CC} – 0.2			V _{CC} – 0.2		V
	I _{OH} = –4 mA	1.65 V	1.29			1.2		
	I _{OH} = –8 mA	2.3 V	1.9			1.7		
	I _{OH} = –12 mA	2.7 V	2.2			2.2		
		3 V	2.4			2.4		
I _{OH} = –24 mA	3 V	2.3			2.2			
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V				0.1	0.2	V
	I _{OL} = 4 mA	1.65 V				0.24	0.45	
	I _{OL} = 8 mA	2.3 V				0.3	0.7	
	I _{OL} = 12 mA	2.7 V				0.4	0.4	
	I _{OL} = 24 mA	3 V				0.55	0.55	
I _I	Control inputs	V _I = 0 to 5.5 V	3.6 V			±1	±5	μA
I _{off}		V _I or V _O = 5.5 V	0			±1	±10	μA
I _{OZ} ⁽¹⁾		V _O = 0 to 5.5 V	3.6 V			±1	±10	μA
I _{CC}	V _I = V _{CC} or GND 3.6 V ≤ V _I ≤ 5.5 V ⁽²⁾	I _O = 0	3.6 V			1	10	μA
						1	10	
ΔI _{CC}		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500	500	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V			4		pF
C _{io}	A or B ports	V _I = V _{CC} or GND	3.3 V			5.5		pF

(1) For I/O ports, the parameter I_{OZ} includes the input leakage current.

(2) This applies in the disabled state only.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			–40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A or B	B or A	1.8 V ± 0.15 V	1	6	12.2	1	12.7	ns
			2.5 V ± 0.2 V	1	3.9	7.8	1	8.3	
			2.7 V	1	4.2	7.1	1	7.3	
			3.3 V ± 0.3 V	1.5	3.8	6.1	1.5	6.3	
t _{en}	OE	A or B	1.8 V ± 0.15 V	1	7	14.8	1	15.3	ns
			2.5 V ± 0.2 V	1	4.5	10	1	10.5	
			2.7 V	1	5.4	9.3	1	9.5	
			3.3 V ± 0.3 V	1.5	4.4	8.3	1.5	8.5	
t _{dis}	OE	A or B	1.8 V ± 0.15 V	1	7.8	16.5	1	17	ns
			2.5 V ± 0.2 V	1	4	9	1	9.5	
			2.7 V	1	4.4	8.3	1	8.5	
			3.3 V ± 0.3 V	1.7	4.1	7.3	1.7	7.5	
t _{sk(o)}			3.3 V ± 0.3 V				1	ns	

SN74LVC245A
OCTAL BUS TRANSCEIVER
WITH 3-STATE OUTPUTS

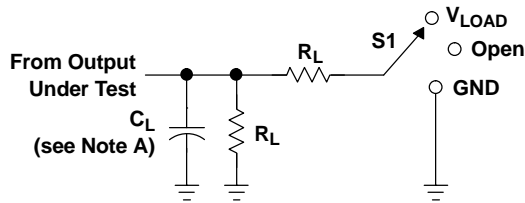
SCAS218T–JANUARY 1993–REVISED FEBRUARY 2005

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT	
C_{pd}	Power dissipation capacitance per transceiver	f = 10 MHz	Outputs enabled	1.8 V	42	pF
				2.5 V	43	
			3.3 V	45		
	Outputs disabled		1.8 V	1		
			2.5 V	1		
			3.3 V	2		

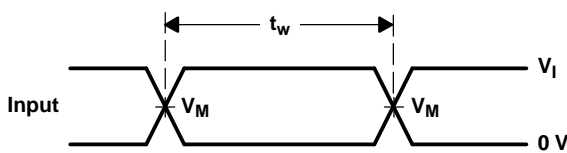
PARAMETER MEASUREMENT INFORMATION



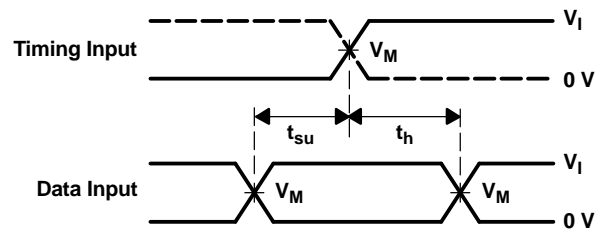
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

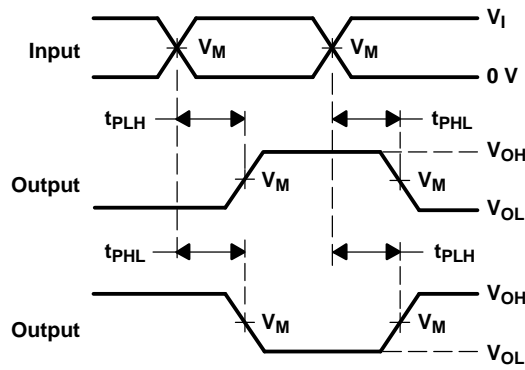
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



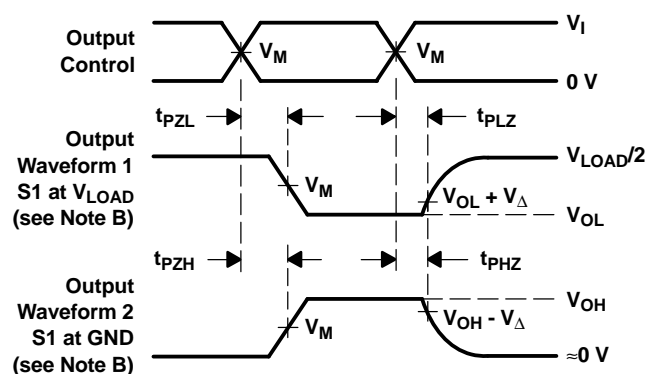
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC245ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74LVC245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245AGQNR	ACTIVE	BGA MICROSTAR JUNIOR	GQN	20	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LVC245AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LVC245ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LVC245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245APWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245APWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74LVC245APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245APWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245APWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245APWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC245APWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC245ARGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LVC245ARGYRG4	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LVC245AZQNR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQN	20	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

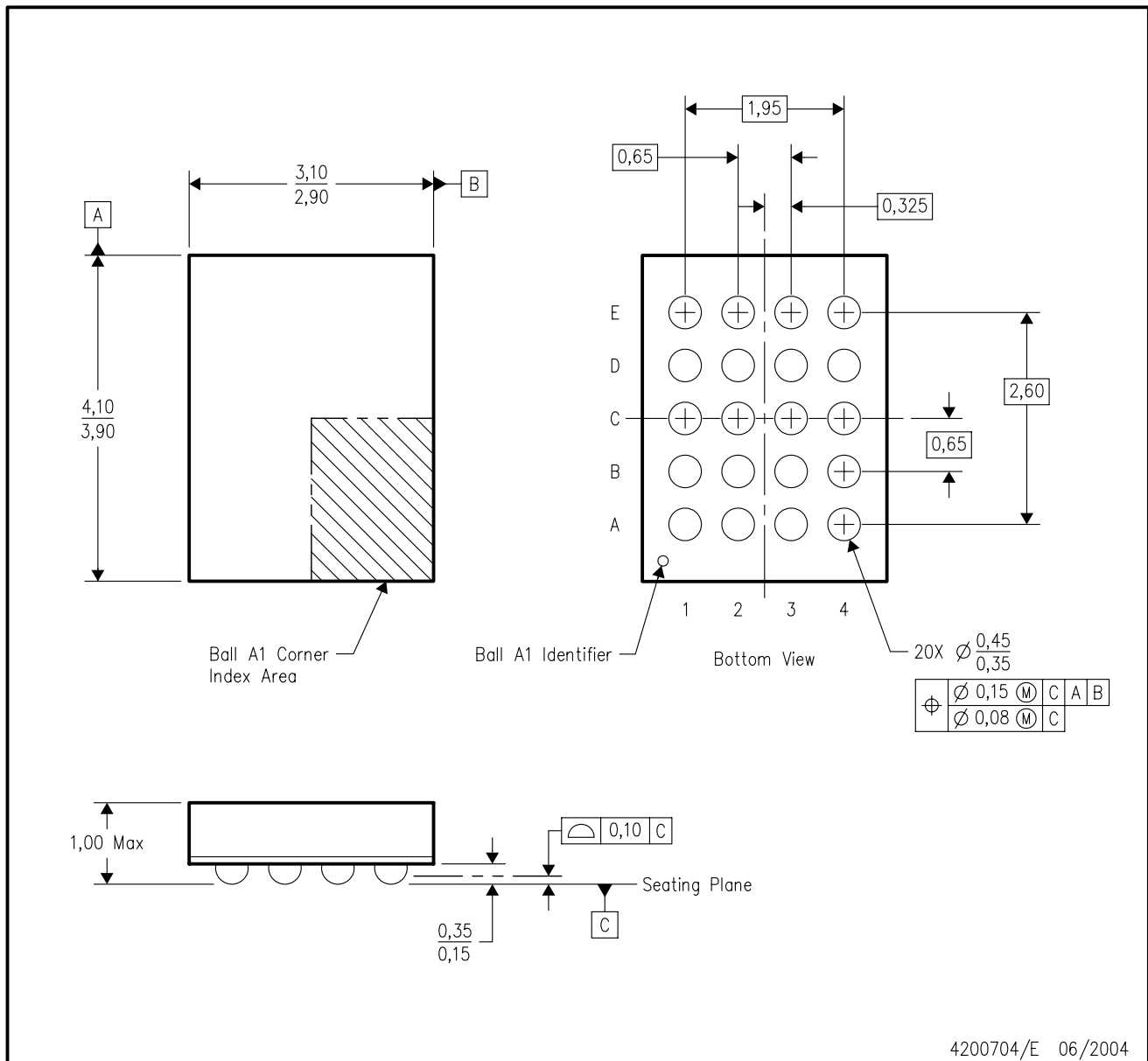
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

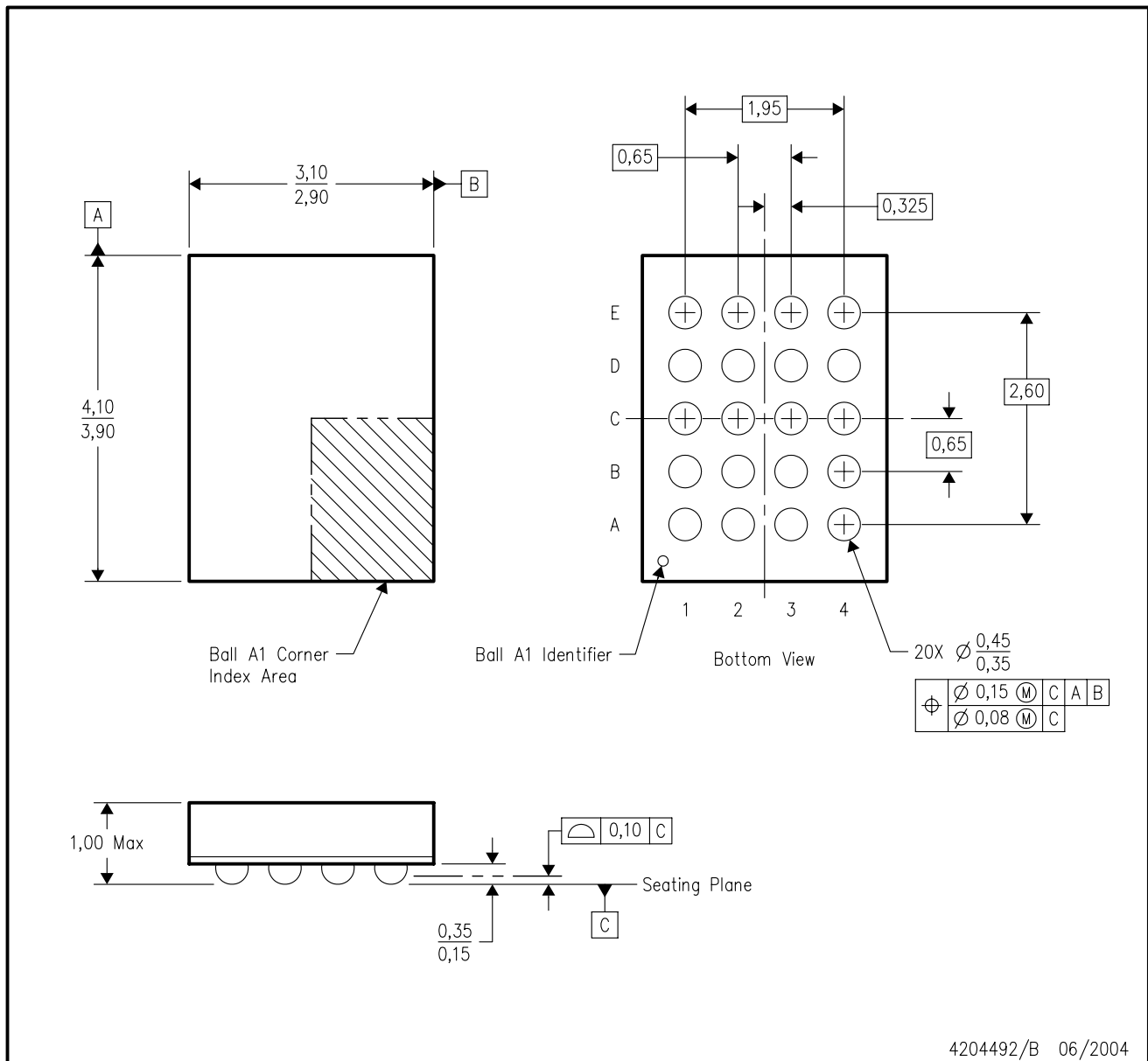


4200704/E 06/2004

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-225 variation BC.
 - D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



4204492/B 06/2004

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-225 variation BC.
 - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

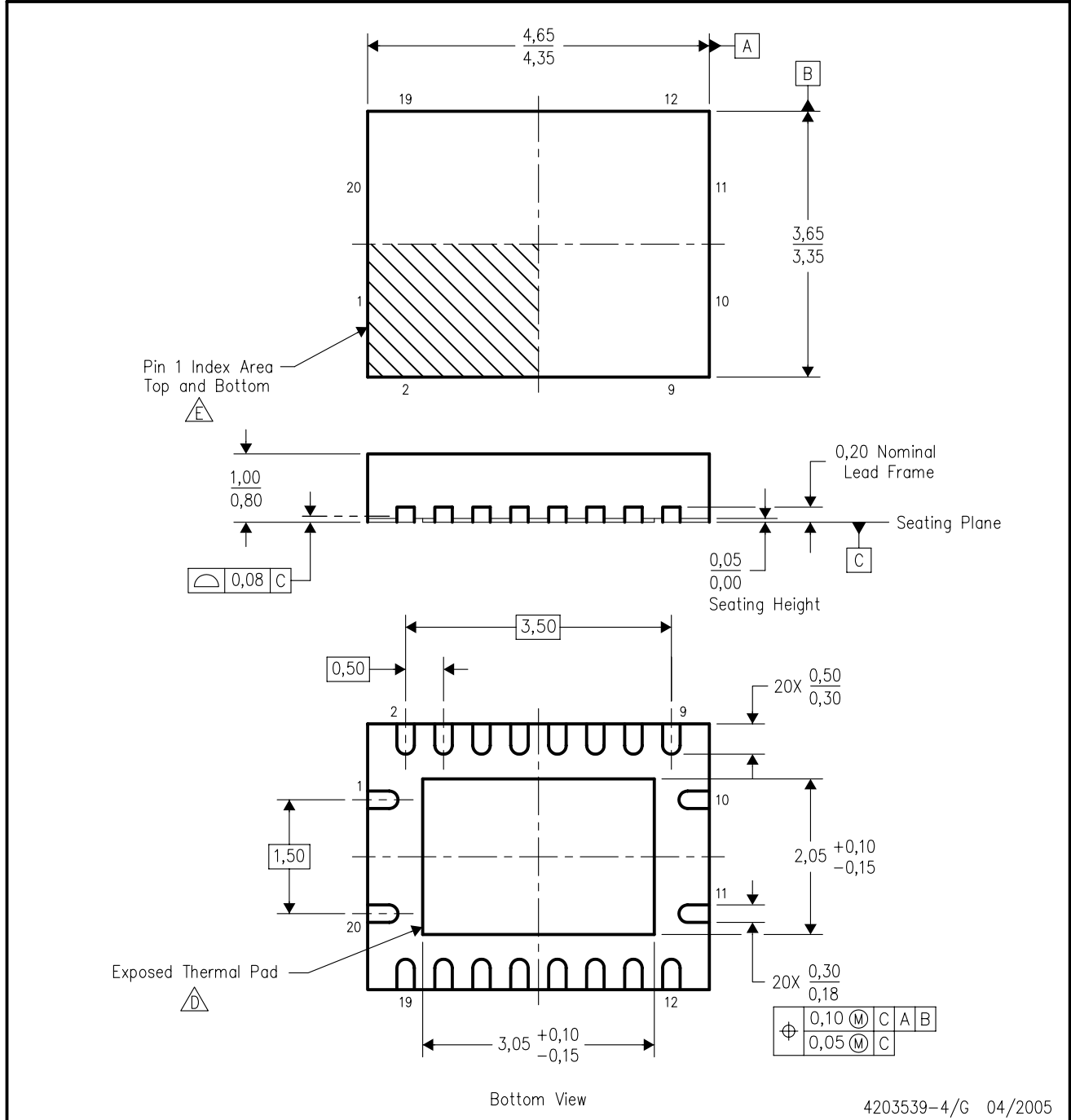
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK



4203539-4/G 04/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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